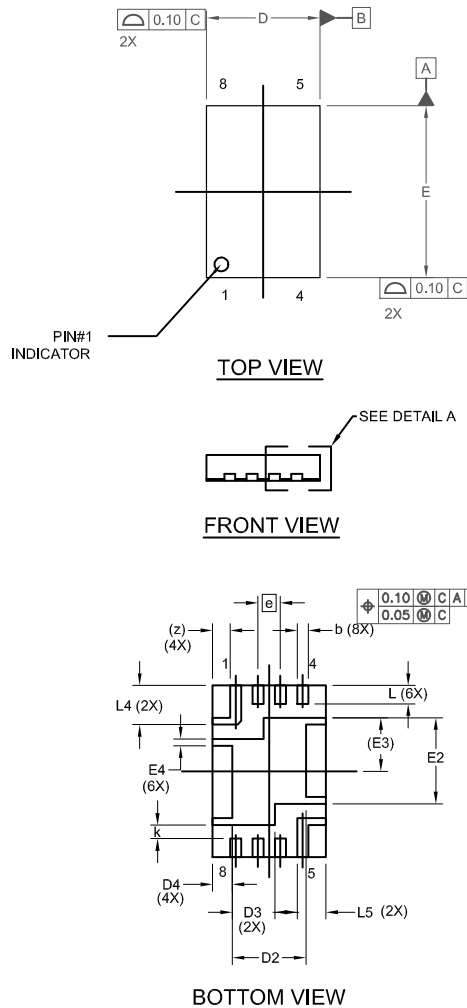
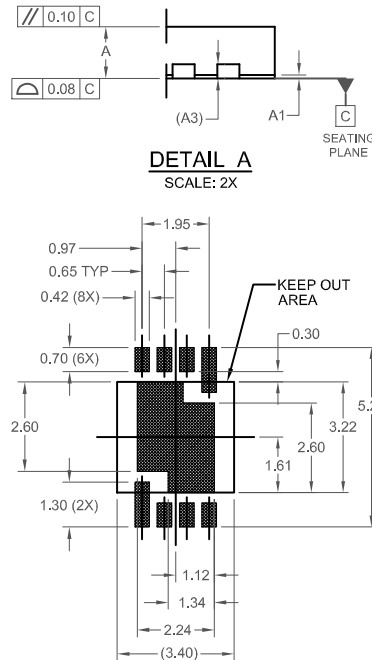


ON

DATE 06 MAY 2021



DETAIL A
SCALE: 2X



LAND PATTERN RECOMMENDATION


*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

NOTES: UNLESS OTHERWISE SPECIFIED

- A) DOES NOT FULLY CONFORM TO JEDEC REGISTRATION, M0229 DATED 8/2012.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A3	0.20 REF		
b	0.27	0.32	0.37
D	3.20	3.30	3.40
D2	2.04	2.14	2.24
D3	1.13	1.23	1.33
D4	0.48	0.58	0.68
E	4.90	5.00	5.10
E2	2.40	2.50	2.60
E3	1.56 REF		
E4	0.10	0.20	0.30
e	0.65 BSC		
k	0.30	0.40	0.50
L	0.44	0.54	0.64
L4	1.04	1.14	1.24
L5	0.75	0.85	0.95
z	0.51 REF		

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